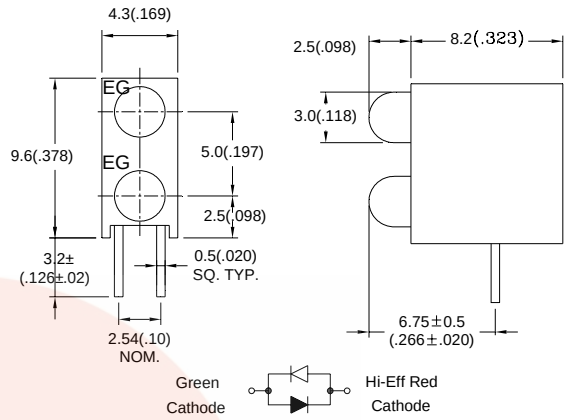
● Features:

1. Chip material: GaAsP/GaP(Red)
   and GaP/GaP(Green)
2. Emitted color : Hi-Eff Red and Green
3. Lens Appearance : White Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

●Package dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

●Absolute Maximum Ratings(Ta=25℃)

Parameter	Symbol	Hi-Eff Red	Green	Unit
Power Dissipation	Pd	80	80	mW
Forward Current	I_F	30	30	mA
Peak Forward Current	I_{FP}	150	150	mA
Reverse Voltage	V_R	5		V
Operating Temperature	Topr	-40℃~85℃		
Storage Temperature	Tstg	-40℃~100℃		
Soldering Temperature	Tsol	260℃max(for 5 seconds)		
Hand Soldering Temperature	Tsol	350℃max(for 3 seconds)		

*[1]Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

●Electrical and optical characteristics(Ta=25℃)

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	I_F=20mA	Hi-Eff Red Green	-	2.0 2.2	2.6 2.6	V
Luminous Intensity	Iv	I_F=20mA	Hi-Eff Red Green	-	12 10	-	mcd
Reverse Current	I_R	V_R=5V	Hi-Eff Red Green	-	-	100	μA
Peak Wave Length	λp	I_F=20mA	Hi-Eff Red Green	-	640 568	-	nm
Dominant Wave Length	λd	I_F=20mA	Hi-Eff Red Green	617 560	-	638 574	nm
Spectral Line Half-width	Δλ	I_F=20mA	Hi-Eff Red Green	-	45 30	-	nm
Viewing Angle	$2\theta_{1/2}$	I_F=20mA	Hi-Eff Red Green	-	40	-	deg

● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensity vs. Wavelength

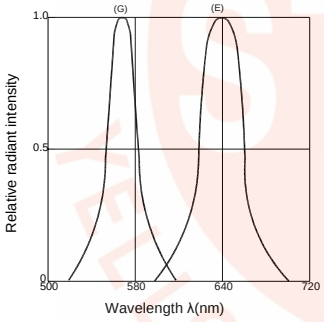


Fig.2 Forward current derating curve vs. Ambient temperature

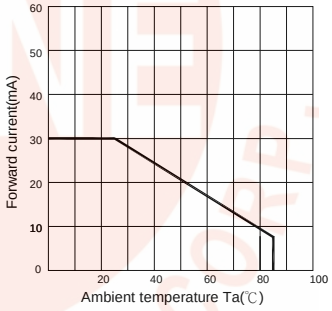


Fig.3 Forward current vs. Forward voltage

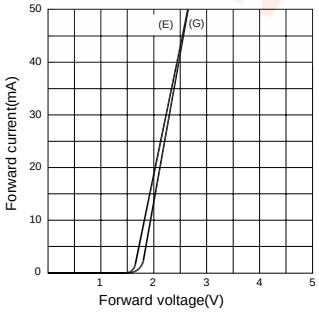


Fig.4 Relative luminous intensity vs. Ambient temperature

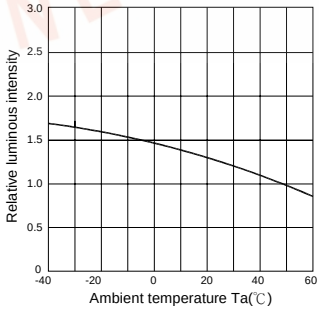


Fig.5 Relative luminous intensity vs. Forward current

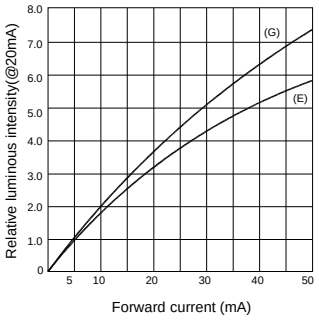
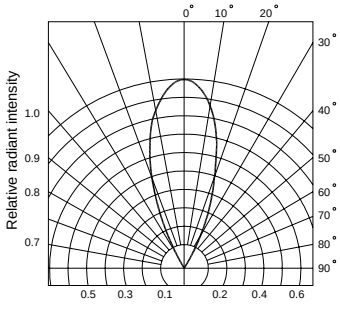
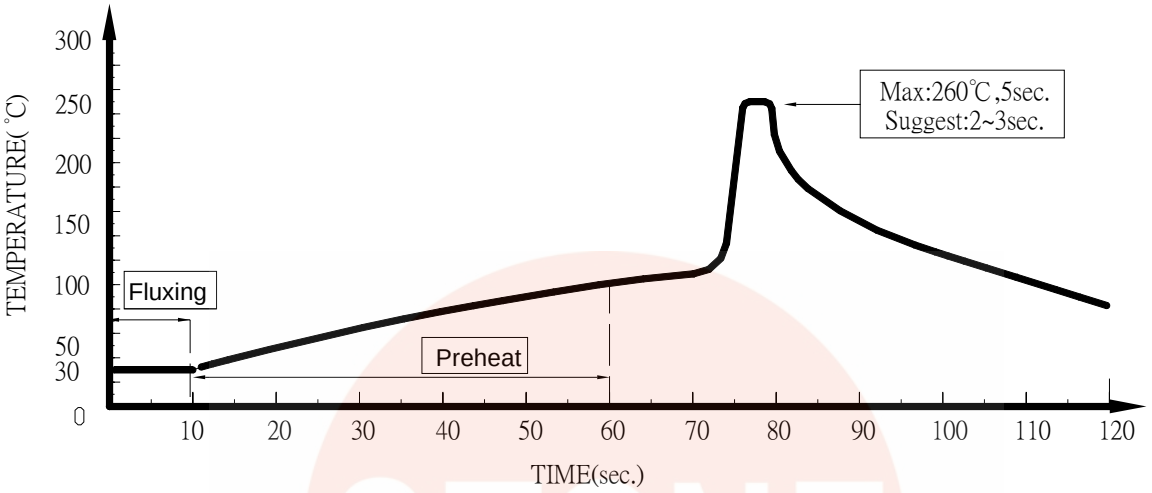


Fig.6 Radiation diagram



● Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature,especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A : Max : 350℃ Within 3 sec. One time only.

B : For 3mm LED without flange, if the LED epoxy lays flat on the PCB, the welding condition is 350℃ within 2 seconds, one time only.